

S-putty

Thermal Conductive Putty

LiPOLY S-putty type is a gel material for gap filling. The thermal conductivity is 2.0~6.0W/m*K. The high deformation material which can filling the gap closely, cover the tolerance, overcome the overflow and drying problem to increase the thermal conductivity. It's the best choice for S-Putty Dispensing Robot.

LiPOLY's ability of research and development is providing our best thermal solution to customers, which can satisfy customer special requirement on advanced product. The product is qualified for UL.



Features-

- Thermal conductivity: 2.0/3.5/6.0 W/m*K
- Tolerance filled
- High compressibility with low stress
- Not vertical flow
- High reliability

Typical Applications-

- For any high compression and low stress application.
- Set top box
- IP CAM

PROPERTY	S-PUTTY5	S-PUTTY	S-PUTTY2	TEST METHOD	UNIT
Color	Blue	Blue	Blue	Visual	-
Resin Base	Silicone	Silicone	Silicone	-	-
Density	2.6	3	3.3	ASTM D792	g/cm ³
Application temperature	-60~180	-60~180	-60~180	-	°C
Bond Line Thickness	100~2000	100~2000	100~2000	-	μm
ELECTRICAL					
Dielectric strength	300	300	300	ASTM D149	V/mil
Volume resistivity	>10 ¹³	>10 ¹³	>10 ¹³	ASTM D257	Ohm-m
THERMAL					
Thermal Conductivity	2	3.5	6	ASTM D5470	W/m*K
Thermal Impedance @10psi	0.097	0.079	0.062	ASTM D5470	°C-in ² /W
Thermal Impedance @ 30psi	0.089	0.071	0.059	ASTM D5470	°C-in ² /W
Thermal Impedance @ 50psi	0.075	0.061	0.053	ASTM D5470	°C-in ² /W
FLAME RATING					
UL Flammability class	V-0	V-0	V-0	UL94	-

※These data are provided for reference only. Engineers are reminded to test the material in varied application.